



MOTOROLA

MVME110/A1

FEBRUARY 1984

ADDENDUM

TO

MVME110-1 VME module MONOBOARD MICROCOMPUTER

USER'S MANUAL

(MVME110/D2)

This addendum makes minor corrections to your MVME110/D2 user's manual. The black change bar in the margin indicates the area of inserted, revised, or deleted material.

Insert change pages attached to this addendum into your MVME110/D2 user's manual. Make certain that the pages you are replacing are removed from your manual. This page of the addendum should be placed after the user's manual title page and used as a record page of the changes made to your manual. Pages affected by this addendum are as follows:

iii/iv
1-3/1-4
2-37/2-38
4-9/4-10
4-19/4-20
5-3/5-4
5-9 through 5-44

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- . A local-memory-decode PROM allows for contiguous addressing between local memory and global VMEbus memory.
- . Two user-configurable jumpers which may be read by the software.
- . Module status and control registers.
- . An MC6840 programmable timer module provides three independent 16-bit counters/timers. Timer outputs may be cascaded for 32- or 48-bit operation.
 - Watchdog timer - uses two MC6840 timers and allows user to generate NMI and RESET if processor fails to periodically restart the counter.
- . Local bus timeout.
- . Interrupt handler for up to seven VME interrupt levels plus up to seven local interrupt levels. The interrupt levels of the seven local interrupt sources are user-selectable. The ABORT pushbutton switch and VME ACFAIL* line are connected to non-maskable interrupt level seven.
- . The RESET and ABORT pushbutton switches may be enabled or disabled by on-board jumpers.
- . Board status indicators.
 - Red FAIL LED indicates module failure.
 - Red HALT LED indicates MPU is halted.
 - Green RUN LED indicates MPU is running.

1.3 SPECIFICATIONS

General specifications for the VME110 are listed in Table 1-1.

TABLE 1-1. VME110 Specifications

| CHARACTERISTIC | SPECIFICATIONS |
|---|--|
| Power requirements (with all eight sockets unpopulated) | +5 Vdc (+ 5%), 2.1 A (typical), 2.4 A (max.) +12 Vdc (+ 5%), 25 mA (typical), 50 mA (max.) -12 Vdc (+ 5%), 25 mA (typical), 50 mA (max.) (see NOTE) |
| Power requirements (with all eight sockets populated) | +5 Vdc (+ 5%), 2.6 A (typical), 3.0 A (max.) +12 Vdc (+ 5%), 25 mA (typical), 50 mA (max.) -12 Vdc (+ 5%), 25 mA (typical), 50 mA (max.) (see NOTE) |
| Temperature | |
| Operating | 0° to 70° C |
| Storage | -55° to +85° C |
| Relative humidity | 0% to 90% (non-condensing) |
| Physical characteristics | Double-high VME board |
| PC board only | |
| Height | 9.2 in. (233 mm) |
| Depth | 6.3 in. (160 mm) |
| Thickness | 0.662 in. (16.77 mm) |
| PC board with connectors and front panel | |
| Height | 10.3 in. (262 mm) |
| Depth | 7.4 in. (188 mm) |
| Thickness | 0.80 in. (20.3 mm) |

NOTE: The currents at +12 Vdc and -12 Vdc are specified for the MVME110 module with the serial port connectors open. The actual required values depend on the load of the RS-232C ports. All serial port outputs are current-limited to sink or source 12 mA (max) each.

1.4 GENERAL DESCRIPTION

The VME110 is a high performance processing module, designed to function as either a stand-alone microcomputer, as a single CPU/system controller in a VMEbus system, or as one of several CPU elements in a multiprocessor VMEbus configuration. This module features the MC68000 16-bit microprocessor with a total address range of 16 megabytes. Sockets are provided to accommodate up to 256K bytes of user-supplied memory. Full support is provided for the I/O Channel which provides access to a large variety of peripheral and industrial I/O functions. An on-board serial communications port is also included.

TABLE 2-27. Map Decoder PROM Hex Codes

| HEX CODE | SELECTED DEVICE |
|----------|--------------------------------------|
| 0 | Illegal |
| 1 | RAM in socket pair 2 |
| 2 | RAM in socket pair 3 |
| 3 | RAM in socket pair 4 |
| 4 | Illegal |
| 5 | WRITE PROTECTED RAM in socket pair 2 |
| 6 | WRITE PROTECTED RAM in socket pair 3 |
| 7 | WRITE PROTECTED RAM in socket pair 4 |
| 8 | PROM in socket pair 1 |
| 9 | PROM in socket pair 2 |
| A | PROM in socket pair 3 |
| B | PROM in socket pair 4 |
| C | VMEbus |
| D | VMEbus |
| E | VMEbus |
| F | VMEbus |

NOTE: Codes 0 and 4 are illegal because RAM may not be installed in socket pair 1. (The processor reads the power-on vector from the PROM's in these sockets.)

Memory chips of different sizes may be used as long as each socket pair contains a matching set. Illustrated in Figure 2-33 is an example configuration which has 8K ROM chips installed in socket pair 1, 4K ROM chips in socket pair 3, and 2K RAM chips in socket pairs 2 and 4. In this case, the memory chips have been arranged so that they form a contiguous 32K block of memory. The two 8K ROM chips in socket pair 1 are placed at the lowest address by programming a hexadecimal "8" into the corresponding decoder PROM locations. The 4K PROM's are placed with hexadecimal "A". The 2K RAM's in socket pair 2 correspond to a hexadecimal "1", and the write protected 2K RAM's in socket pair 4 correspond to the hex codes of "7" and "3".

Because the rest of the local memory block is not needed, the decoder PROM locations are programmed with a hex "F". This causes the board to access the VMEbus whenever that area of the map is addressed. If there is a memory board on the VMEbus which contains that address, it will be contiguous with the local memory.

It should be noted that the socket pairs do not necessarily appear in the map in order (socket pairs 1, 3, 2, 4). The placement of the chips into the 28-pin socket pairs does not govern their placement in the memory map. There are some restrictions, however. In the example just described, if the user wanted to rearrange the chips in the order 1, 2, 3, 4, he would run into difficulty. This is because the 8K of memory in socket pair 3 has to be placed on a 4K boundary. Therefore, it could not be contiguous with the 4K of memory in socket pair 2 below it in the memory map.

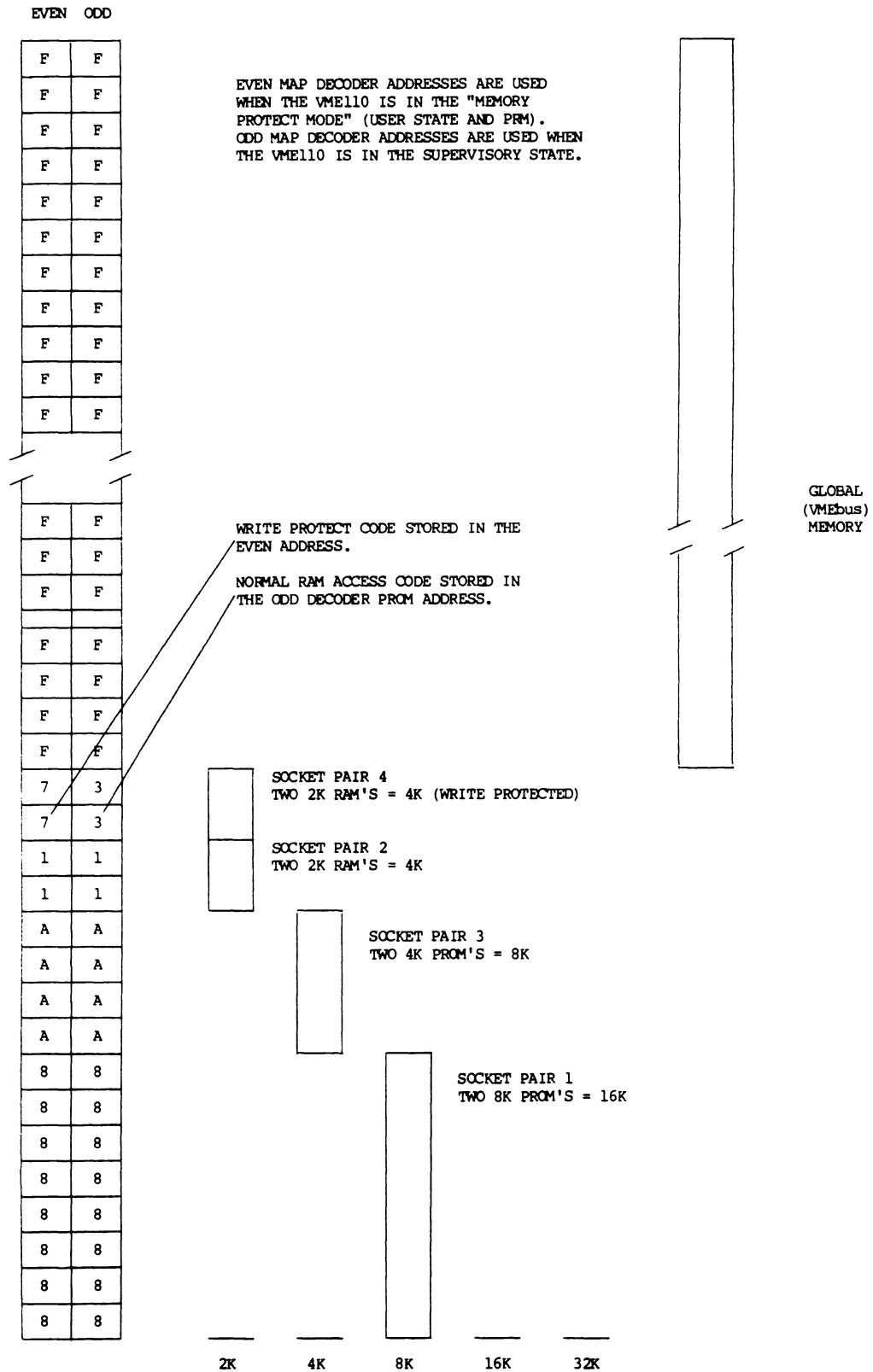


FIGURE 2-33. Map Decoder PROM Example

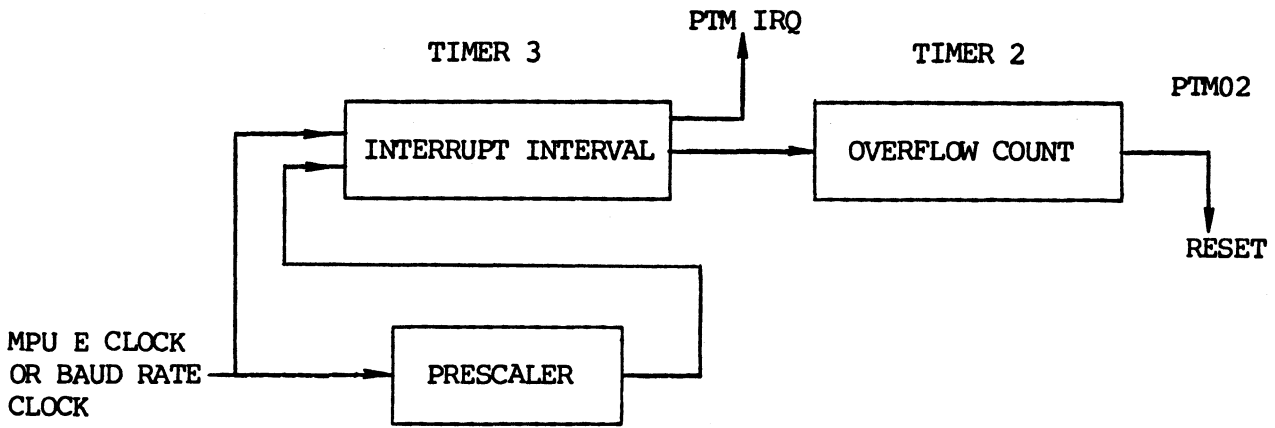


FIGURE 4-5. PIM Watchdog Timer Configuration

4.3.4.2 Asynchronous Communication Interface Adapter (ACIA). The Serial Port consists of an MC6850 ACIA, RS-232C connector and interface, and baud rate select circuitry. The port is configured as Data Communication Equipment (DCE) to be connected to Data Terminal Equipment (DTE). Table 5-3 lists the serial port connector signals. The user should refer to the ACIA data sheet for detailed register descriptions.

The following paragraph covers any special initialization procedures or considerations.

The user should perform a master reset to the ACIA after each MPU reset to ensure proper ACIA initialization. The count divide select should be selected for divide by sixteen. The ACIA Request To Send (\overline{RTS}) signal controls the serial port Clear To Send signal (CTS). Normally, the \overline{RTS} signal should be low to allow the terminal to transmit data. If the user wishes to implement flow control, the \overline{RTS} signal may be set high. This causes the CTS signal to the terminal to indicate an off condition and inhibit data transmission. The ACIA Data Carrier Detect (\overline{DCD}) input is permanently set low. The ACIA \overline{CTS} signal is low whenever the terminal indicates it is ready.

Two optional capacitors may be installed at C43 and C44 for controlling the slew rate of the Transmit Data (TXD) and Data Terminal Ready (DTR) signals. In noisy environments, the addition of the capacitor allows the rejection of high frequency noise. Refer to the MCL489 data sheet for additional information.

4.3.4.3 Module Control Register (MCR). Memory map address FE8021 is reserved for addressing the MCR (U37).

The MCR contains six bits for controlling various board functions as described below. The MCR may only be written while in the supervisor state. A bus error will be issued if a write attempt is made while in the user state.

Upon initialization, the MCR is reset to \$10, which illuminates the FAIL indicator.

| | | | | | | | |
|-----|-----|------|------|---|---|------|------|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| PRM | WDE | SFIE | FAIL | 0 | 0 | BRC1 | BRC0 |

- PRM - PROTECT MODE
0 Protect Mode disabled.
1 Protect Mode enabled.
- WDE - WATCHDOG ENABLE
0 Watchdog Timer disabled.
1 Watchdog Timer enabled.
- SFIE - SYSTEM FAIL INTERRUPT ENABLE
0 interrupt disabled.
1 interrupt enabled.
- FAIL - 0 No Failure. The FAIL indicator is extinguished and the VMEbus SYSFAIL* signal is deactivated.
1 Failure. The FAIL indicator is illuminated and the VMEbus SYSFAIL* signal is activated.

BRC1, BRC0 - BUS RELEASE CONTROL BITS

| BRC1 | BRC0 | MODE SELECTED |
|------|------|----------------------------|
| 0 | 0 | ROR - Release on request |
| 0 | 1 | RBC - Release on bus clear |
| 1 | 0 | RWD - Release when done |
| 1 | 1 | RNE - Release never |

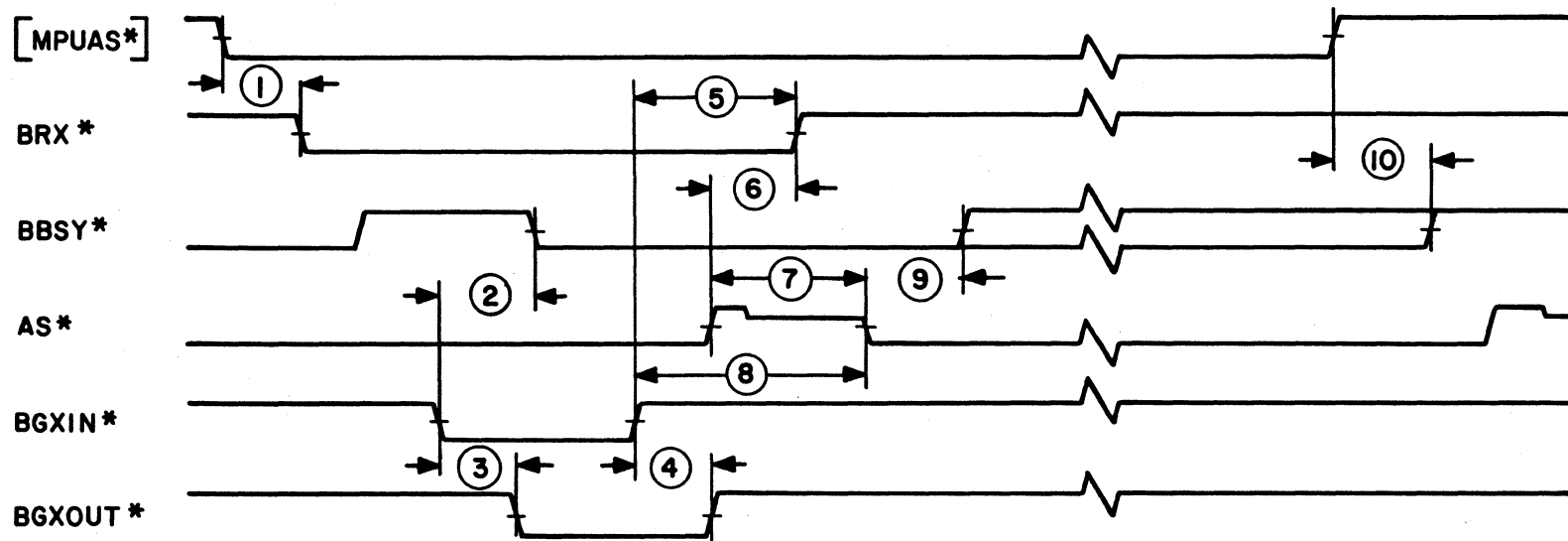
Refer to paragraph 4.3.9.2 for details of these release modes.

4.3.4.4 Module Status Register (MSR). The MSR (U52) is addressed using address FE8031 of the memory map.

The MSR allows the user to read the current level of ACFAIL*, SYSFAIL*, and the user configurable jumpers. The MSR is a read-only register. Any write attempt to this register results in a bus error.

| | | | | |
|-----|----|------|------|-----------|
| 7 | 6 | 5 | 4 | 0-3 |
| ACF | SF | SSB1 | SSB0 | UNDEFINED |

- ACF - AC FAILURE
0 VMEbus ACFAIL* false.
1 VMEbus ACFAIL* true.
- SF - SYSTEM FAILURE
0 VMEbus SYSFAIL* false.
1 VMEbus SYSFAIL* true.
- SSB1 - SOFTWARE STATUS BIT 1
0 Header J5 pins 3 and 5 connected.
1 Header J5 pins 1 and 3 connected.
- SSB0 - SOFTWARE STATUS BIT 0
0 Header J5 pins 4 and 6 connected.
1 Header J5 pins 2 and 4 connected.



NOTE: IN THE SIGNAL NAMES ABOVE, X IS THE ARBITRATION REQUEST LEVEL SELECTED ON HEADERS J2 AND J3.

FIGURE 4-9. VMEbus Requester Timing Diagram

ROR - Release on Request. Once bus mastership has been granted, it is released when any potential bus master requests use of the bus. This mode is selected at reset and is intended for systems in which the VME110 is the primary user of the bus.

RWD - Release when Done. Once bus mastership has been granted, it is immediately released shortly after the beginning of the cycle. Arbitration of the next bus cycle may occur concurrently with the completion of the present bus cycle. Arbitration will be required on each VME110 bus cycle. This mode is useful to guarantee quick bus availability to other bus masters in the system.

The chart below demonstrates how MPU performance and VMEbus performance are affected by the various release modes.

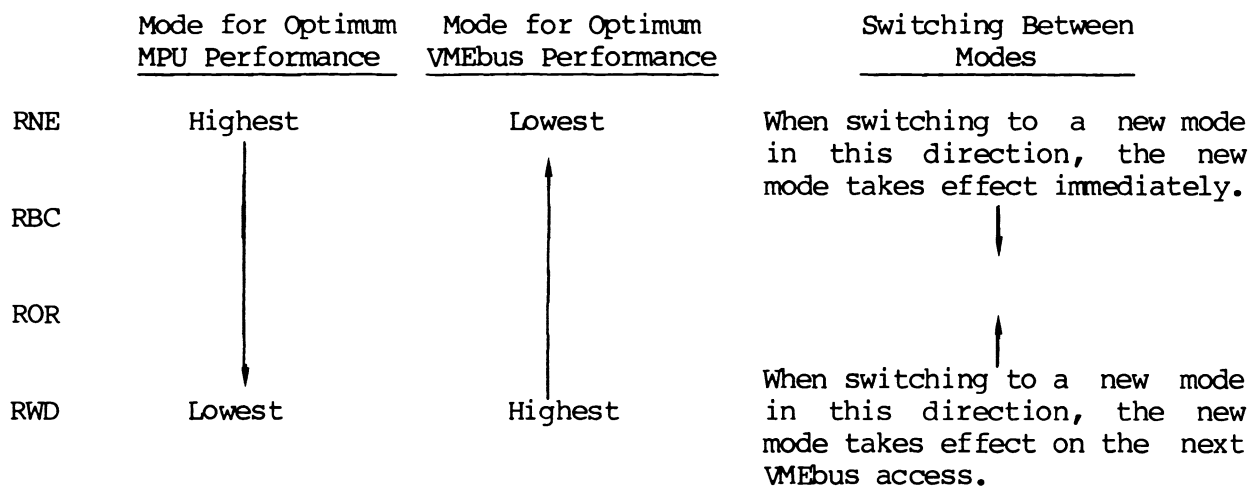


TABLE 4-6. Requester Timing

| NO. | CHARACTERISTIC | TYP | MAX |
|-----|---|-----|-----|
| 1 | [MPUAS*] low to BRX* low | 60 | 70 |
| 2 | BGXIN* low to BBSY* low | 110 | 125 |
| 3 | BGXIN* low to BGXOUT* low | 35 | 50 |
| 4 | BGXIN* high to BGXOUT* high | 20 | 30 |
| 5 | BGXIN* high to BRX* released | 95 | 120 |
| 6 | AS* high to BRX* released | 60 | 95 |
| 7 | AS* high pulse width | 115 | 150 |
| 8 | BGXIN* high to AS* low | 130 | 175 |
| 9 | AS* low to BBSY* high (RWD Mode) | 45 | 65 |
| 10 | [MPUAS*] high to BBSY* high (ROR and RBC Modes) (See Note) | 35 | 50 |

NOTE: In the ROR and RBC modes, if the release condition is present, the bus will be released within time #10 after the completion of the current MPU cycle. The bus will also be released within time #10 after an MPU halt condition.

TABLE 5-1. VMEbus Connector P1 Pin Assignments (cont'd)

| PIN NUMBER | SIGNAL MNEMONIC | SIGNAL NAME AND DESCRIPTION |
|-------------------|---------------------|---|
| A24 | A07 | ADDRESS bus (bit 7) - One of 23 three-state driven output lines which specify an address in the memory map (see Figure 4-3). |
| A25 | A06 | ADDRESS bus (bit 6) - Similar to pin A24. |
| A26 | A05 | ADDRESS bus (bit 5) - Similar to pin A24. |
| A27 | A04 | ADDRESS bus (bit 4) - Similar to pin A24. |
| A28 | A03 | ADDRESS bus (bit 3) - One of 23 three-state driven output lines which specify a memory address. During an interrupt acknowledge cycle, address bus lines 1-3 are used to indicate the interrupt level which is being acknowledged. |
| A29 | A02 | ADDRESS bus (bit 2) - Similar to pin A28. |
| A30 | A01 | ADDRESS bus (bit 1) - Similar to pin A28. |
| A31 | -12V | -12 Vdc power - used by logic circuits. |
| A32 B32 C32 | +5V | +5 Vdc power - used by logic circuits. |
| B1 | BBSY* | BUS BUSY - This bidirectional signal is driven low when the VME110 is the VMEbus master. Also an input to the arbiter to indicate that the bus may be arbitrated. |
| B2 | BCLR* | BUS CLEAR - Input signal that causes the release of bus mastership in the RBC mode. |
| B3 | ACFAIL* | AC FAILURE - Input signal that indicates a power failure has occurred and generates a level seven interrupt request. |
| B4,B6, B8,B10 | BG0IN*- BG3IN* | BUS GRANT (0-3) IN - Bus-grant-in and bus-grant-out form a daisy-chained bus grant. A grant received at the jumpered level indicates the VME110 may become the bus master. The remaining three bus-grant-in lines are connected directly to their respective bus-grant-out lines. |
| B5,B7, B9,B11 | BG0OUT*- BG3OUT* | BUS GRANT (0-3) OUT - Bus-grant-in and bus-grant-out form a daisy-chained bus grant. When a bus-grant-in is received at the jumpered level and the MPU is not awaiting bus mastership, the bus-grant-out signal is true on the respective level. |

TABLE 5-1. VMEbus Connector P1 Pin Assignments (cont'd)

| PIN NUMBER | SIGNAL MNEMONIC | SIGNAL NAME AND DESCRIPTION |
|------------|--------------------|---|
| B12-15 | BR0*-BR3* | BUS REQUEST (0-3) - The bidirectional bus request of the jumpered level is true when the MPU requires bus mastership. When one or more of the bus request lines is true in the ROR mode, bus mastership is released. When the VME110 is the system controller, bus request level three is monitored by the arbiter. |
| B16-19 | AM0-AM3 | ADDRESS MODIFIER (bits 0-3) - Similar to pin A23. |
| B21 | SERCLK | Not used. |
| B22 | SERDAT | Not used. |
| B24-30 | IRQ7*- IRQ1* | INTERRUPT REQUEST (7-1) - Seven prioritized interrupt request inputs. Jumper enabled, level seven is the highest priority. |
| B31 | +5V STDBY | Not used. |
| C1-8 | D08-D15 | DATA BUS (bits 8-15) - Eight of 16 three-state bidirectional data lines which provide the data path between VMEbus master and slave. Similar to pins A1-8. |
| C10 | SYSFAIL* | SYSTEM FAIL - Reflects state of FAIL bit in MCR and FAIL indicator. When enabled in MCR, this bidirectional signal generates an interrupt request. |
| C11 | BERR* | BUS ERROR - Indicates an error has occurred during data transfer cycle. The cycle is terminated and the MPU starts exception processing. When the VME110 is the system controller, this bidirectional signal is generated when a data transfer cycle did not complete within 200 us. |
| C12 | SYSRESET* | SYSTEM RESET - Causes a board level reset when received from the VMEbus. When system controller, a board level reset causes this bidirectional signal to be generated to the VMEbus (see Figure 4-2). |
| C13 | LWORD* | LONGWORD - Not driven. This terminated signal remains at a high level when the VME110 is bus master. |
| C14 | AM5 | ADDRESS MODIFIER (bit 5) - This output line is not driven by the VME110. AM5 always appears as a high (true) level on the VMEbus because of the backplane termination. |
| C15 | A23 | ADDRESS bus (bit 23) - Similar to pin A24. |

TABLE 5-4. VME110 Parts List

| REFERENCE DESIGNATION | MOTOROLA PART NUMBER | DESCRIPTION |
|--|----------------------|---|
| | 84-W8047B01 | PWB assembly, VME110 |
| C1-9,C13-30, C41,C42 | 21SW992C025 | Capacitor, ceramic, .100 uF @ 50 Vdc |
| C10,C11, C31-40 | 21NW9702A09 | Capacitor, ceramic, .1 uF @ 50 Vdc |
| C12 | 21NW9604A11 | Capacitor, ceramic, .47 uF @ 50 Vdc, <u>±</u> 20% |
| C43,C44 | (see NOTE 1) | |
| C45 | 23NW9618A33 | Capacitor, 22 uF @ 25 Vdc |
| DL1 | 01NW9804B83 | Delay, 50 nsec |
| DL2 | 01NW9804C34 | Delay line, triple, 70 nsec |
| DS1,DS2 | 48NW9612A34 | Indicator light, red, 5 Vdc |
| DS3 | 48NW9612A38 | LED, green |
| J1,J4,J6,J13 | 28NW9802D04 | Header, single-row post, 3-position |
| J2,3 | 28NW9802C63 | Header, double-row post, 12-pin |
| J5 | 28NW9802B21 | Header, double-row post, 6-pin |
| J7 | 28NW9802E30 | Header, single-row post, 4-position |
| J8,J9,J10, J14,J16-27 | 28NW9802C43 | Header, double-row post, 8-pin |
| J11,J12 | 28NW9802C36 | Header, double-row post, 14-pin |
| J15 | 28NW9802D88 | Connector, RS-232C |
| P1 | 28NW9802E51 | Connector, 96-pin plug |
| P2 | 28NW9802E05 | Connector, 64-pin plug |
| R1,R2,R4,R6, R7,R14,R16, R18,R22 | 06SW-124A65 | Resistor, film, 4.7k ohm, 5%, 1/4 W |
| R3,R19,R20 | 51NW9626A49 | Resistor network, seven 10k ohm |
| R5,R15 | 06SW-124A37 | Resistor, film, 330 ohm, 5%, 1/4 W |
| R8,R11,R12 | 51NW9626A37 | Resistor network, nine 10k ohm |

TABLE 5-4. VME110 Parts List (cont'd)

| REFERENCE DESIGNATION | MOTOROLA PART NUMBER | DESCRIPTION |
|-----------------------|----------------------|---|
| R9,10 | 06SW-124B22 | Resistor, film, 1M ohm, 5%, 1/4 W |
| R13 | 51NW9626A41 | Resistor network, nine 4.7k ohm |
| R17 | 51NW9626A76 | Resistor network, six 330/470 ohm |
| R21 | 51NW9626A46 | Resistor network, five 4.7k ohm |
| S1,S2 | 40NW9801A54 | Switch, SPDT |
| U1,U35 | 51NW9615F38 | I.C. SN74LS393N |
| U2 | 51NW9615C95 | I.C. SN74S74N |
| U3 | (See NOTE 2) | I.C. Programmed PROM |
| U4 | 51NW9615G97 | I.C. MC68000G8 |
| U5,U6 | 51NW9615H89 | I.C. SN74LS645-1N |
| U7 | 51NW9615F10 | I.C. SN74LS125AN |
| U8,U39,U40 | 51NW9615C96 | I.C. SN74S04N |
| U9,U54 | 51NW9615D32 | I.C. SN74S02N |
| U10,U48 | 51NW9615E91 | I.C. SN74LS00N |
| U11 | (See NOTE 2) | I.C. Programmed PROM |
| U12,U16,U58 | 51NW9615C94 | I.C. SN74S00N |
| U13,U14, U25,U26 | 51NW9615F65 | I.C. SN74S241N |
| U15 | 51NW9615B65 | I.C. MC1455P1 |
| U17,U49 | 51NW9615F41 | I.C. DM74LS164N |
| U18,U61 | 51NW9615E27 | I.C. 74S10PC |
| U19 | 51NW9615D26 | I.C. 74S113N |
| U20 | 51NW9615A36 | I.C. MC7406P |
| U21,U34,U38 | 51NW9615C21 | I.C. SN74LS04N |
| U22 | (See NOTE 2) | I.C. Programmed PROM |
| U23 | 51NW9615D31 | I.C. 82S131F Programmable PROM (see NOTE 3) |

TABLE 5-4. VME110 Parts List (cont'd)

| REFERENCE DESIGNATION | MOTOROLA PART NUMBER | DESCRIPTION |
|-----------------------|----------------------|--|
| U24,U33,U45 | 51NW9615F85 | I.C. SN74S38N |
| U27 | 51NW9615G38 | I.C. SN74LS38N |
| U28 | 51NW9615G81 | I.C. SN74LS132N |
| U29 | 51NW9615E33 | I.C. 74S03A |
| U30 | (See NOTE 2) | I.C. Programmed PROM |
| U31 | 51NW9615G10 | I.C. SN74LS148N |
| U32 | 51NW9615E86 | I.C. SN74LS151N |
| U36 | 51NW9615E93 | I.C. SN74LS14N |
| U37 | 51NW9615C29 | I.C. SN74LS174N |
| U41 | 51NW9615E77 | I.C. SN74LS27N |
| U42 | 51NW9615E99 | I.C. SN74LS374N |
| U43,U44 | 51NW9615C22 | I.C. SN74LS08N |
| U46 | 51NW9615D27 | I.C. SN74S32N |
| U47 | 48AW1019B01 | K1135 Dual baud rate generator |
| U50 | 51NW9615J11 | I.C. SN74S140N |
| U51 | 51NW9615H53 | I.C. SN74LS09N |
| U52,U55,U59 | 51NW9615F02 | I.C. 74LS244N |
| U53 | 51NW9615F59 | I.C. MC68B40P |
| U56 | 51NW9615B29 | I.C. MC1488L |
| U57 | 51NW9615D86 | I.C. MC68B50P |
| U60 | 51NW9615B30 | I.C. MC1489AL |
| U62 | 51NW9615H57 | I.C. SN74LS194AN |
| U63 | 51NW9615E96 | I.C. SN74LS245 |
| Y1 | 48AW1016B01 | Crystal oscillator, 16.0 MHz \pm 0.05% |
| | 02SW990D001 | Nut, hex M 2.5 x .45 x 2 (2 req'd) |
| | 02SW990D007 | Nut, hex M 2 x .4 x 1.6 (4 req'd) |

TABLE 5-4. VME110 Parts List (cont'd)

| REFERENCE DESIGNATION | MOTOROLA PART NUMBER | DESCRIPTION |
|-----------------------|----------------------|---|
| | 03SW993D110 | Screw, phillips, M 2 x .4 x 10 (4 req'd) |
| | 03SW993D210 | Screw, phillips, M 2.5 x .45 x 10 (3 req'd) |
| | 03SW993D208 | Screw, phillips, M 2.5 x .45 x 8 (2 req'd) |
| | 04SW997D003 | Washer, M 2.5 x .6 (2 req'd) |
| | 04SW999D005 | Washer, flat, M 2.7 x .5 (2 req'd) |
| | 07-W4252B01 | Bracket, card mounting (3 req'd) |
| | 09NW9811A04 | Socket, I.C., DIL, 16-pin, low profile (Use at U23) |
| | 09NW9811A09 | Socket, I.C., DIL, 18-pin, low profile (Use at U47) |
| | 09NW9811A34 | Socket, I.C., DIL, 64-pin (Use at U4) |
| XU1-XU8 | 09NW9811A64 | Socket, I.C., DIL, 28-pin |
| | 09NW9811A78 | Socket, I.C., DIL, 20-pin (Use at U3, U11, U22, U30) |
| | 09NW9811A46 | Socket, 4-lead crystal oscillator (Use at Y1) |
| | 29NW9805B17 | Jumper, shorting insulated (Use at J1-J14, J16-J27) |
| | 38NW9404B97 | Cap, large snap-on, black |
| | 38NW9404C04 | Cap, snap-on, red |
| | 64-W4629B01 | Panel, front, MVME100 (alternate is 64-W4301B01) |
| | 55NW9501A10 | Handle, VME, single-wide (2 req'd) (See NOTE 4) |
| | 33-W4602B01 | Nameplate, MVME110 |
| | 33-W4643B01 | Nameplate, VME, blank |
| | 43NW9002B25 | Bushing, retainer, metric (2 req'd) (See NOTE 4) |

TABLE 5-4. VME110 Parts List (cont'd)

| REFERENCE DESIGNATION | MOTOROLA PART NUMBER | DESCRIPTION |
|-----------------------|----------------------|---|
| | 03NW9004B48 | Screw, captive, M 2.5 (2 req'd) (See NOTE 4) |
| | 03NW9004B49 | Screw, phillips, M 2.5 x 7 (See NOTE 4) |
| | 03NW9004B44 | Screw, pan-head, M 2.5 x 16 (2 req'd) (See NOTE 4) |
| | 33-W4365B02 | Label, I.D., module |

- NOTES:
- (1) C43 and C44 are optional capacitors which are not installed but may be, at the discretion of the user. Refer to paragraph 4.3.4.2.
 - (2) When ordering, use number labeled on part. For programming details, see Appendix A.
 - (3) Must be programmed by user. Refer to paragraph 2.3.15.
 - (4) Used only with the part number 64-W4629B01.

5.4 SCHEMATIC DIAGRAMS

Figure 5-2 (14 sheets) contains detailed schematic diagrams of the various internal modules comprising the VME110. These schematic diagrams represent the latest design. Occasionally, minor component changes are made at the factory. Therefore, when replacing a component, always use the same value as the defective component even though the schematic diagram may indicate a different value or type.

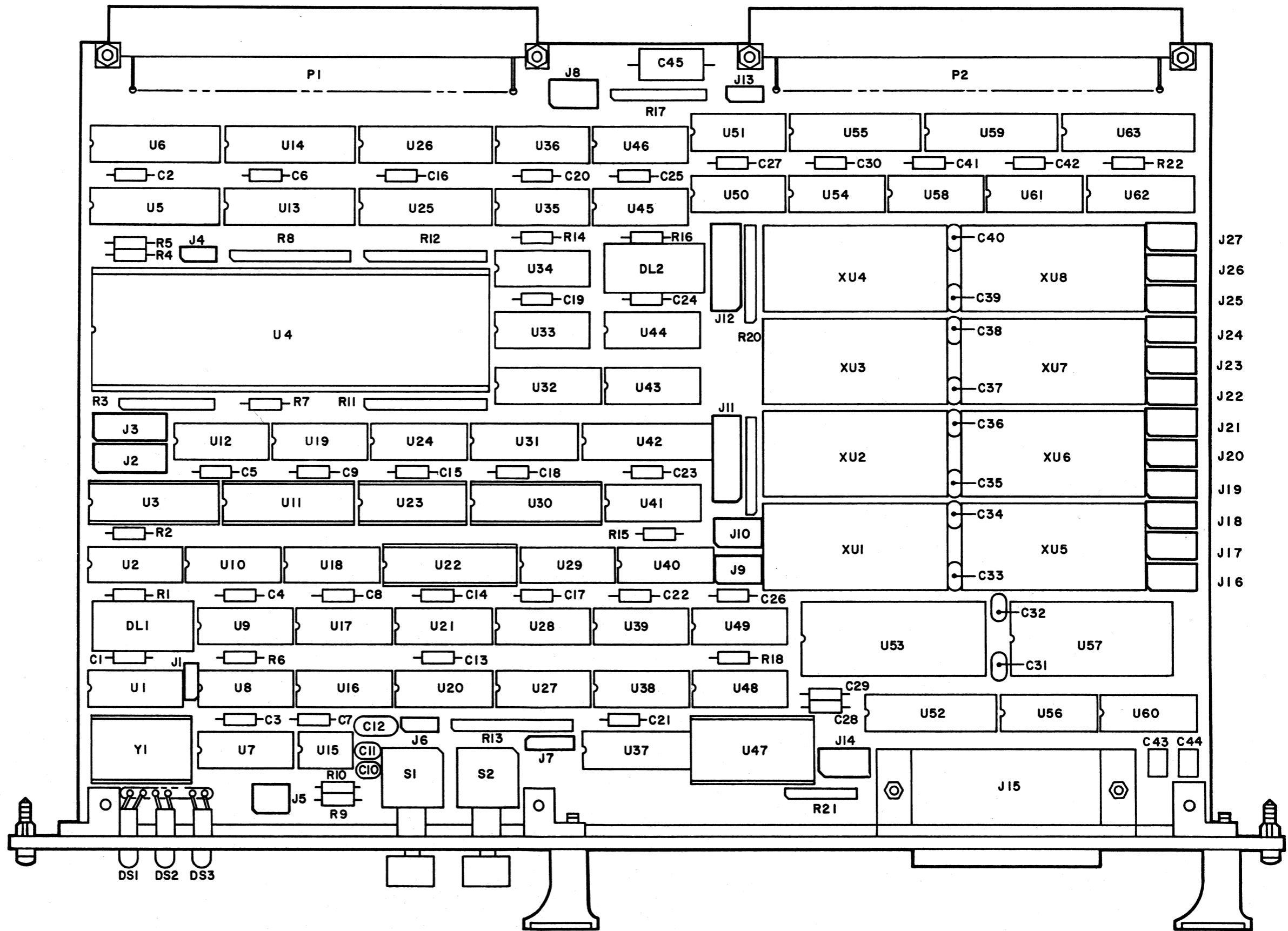


FIGURE 5-1. VME110 Module Parts Location Diagram

8 7 6 5 4 3 2 1

NOTES:
 1. FOR REFERENCE DRAWINGS REFER TO BILL(S) OF MATERIAL 01-W3047B01.
 2. UNLESS OTHERWISE SPECIFIED:
 ALL RESISTORS ARE IN OHMS, ± 5PCT, 1/4 WATT.
 ALL CAPACITORS ARE IN UF.
 ALL VOLTAGES ARE DC.

3. INTERRUPTED LINES CODED WITH THE SAME LETTER OR LETTER COMBINATIONS ARE ELECTRICALLY CONNECTED.
 4. DEVICE TYPE NUMBER IS FOR REFERENCE ONLY. THE NUMBER VARIES WITH THE MANUFACTURER.
 5. SPECIAL SYMBOL USAGE:
 * DENOTES - ACTIVE LOW SIGNAL.
 [] DENOTES - ON BOARD SIGNAL.
 6. INTERPRET DIAGRAM IN ACCORDANCE WITH AMERICAN NATIONAL STANDARDS INSTITUTE SPECIFICATIONS, CURRENT REVISION.

7. PART TYPES ARE ABBREVIATED IN THE FIELD OF THE DRAWING, FOR FULL PART TYPE, REFER TO TABLE 1.
 8. NOT INSTALLED, USERS OPTION.
 9. NUMBERS IN PARENTHESES ARE FOR 24 PIN DEVICES. REFER TO MANUFACTURER'S CATALOGUE FOR MNEMONICS.
 10. PART MOUNTED ON FRONT PANEL.

TABLE 1

| REF DES | TYPE | GND | +5V | +12V | -12V |
|---------|-----------|-------|-------|------|------|
| U1 | 74LS393 | 7 | 14 | | |
| U2 | 74S74 | 7 | 14 | | |
| U3 | PAL16L8 | 10 | 20 | | |
| U4 | MC68000L8 | 53,16 | 49,14 | | |
| U5 | 74LS645-1 | 10 | 20 | | |
| U6 | 74LS645-1 | 10 | 20 | | |
| U7 | 74LS125 | 7 | 14 | | |
| U8 | 74S04 | 7 | 14 | | |
| U9 | 74S02 | 7 | 14 | | |
| U10 | 74LS00 | 7 | 14 | | |
| U11 | PAL16L8 | 10 | 20 | | |
| U12 | 74S00 | 7 | 14 | | |
| U13 | 74S241 | 10 | 20 | | |
| U14 | 74S241 | 10 | 20 | | |
| U15 | MC1455 | 1 | 8 | | |
| U16 | 74S00 | 7 | 14 | | |
| U17 | 74LS164 | 7 | 14 | | |
| U18 | 74S10 | 7 | 14 | | |
| U19 | 74S113 | 7 | 14 | | |
| U20 | 7406 | 7 | 14 | | |
| U21 | 74LS04 | 7 | 14 | | |
| U22 | PAL16L8 | 10 | 20 | | |
| U23 | 82S131 | 8 | 16 | | |
| U24 | 74S38 | 7 | 14 | | |
| U25 | 74S241 | 10 | 20 | | |
| U26 | 74S241 | 10 | 20 | | |
| U27 | 74LS38 | 7 | 14 | | |
| U28 | 74LS132 | 7 | 14 | | |
| U29 | 74S03 | 7 | 14 | | |
| U30 | PAL16L8 | 10 | 20 | | |
| U31 | 74LS148 | 8 | 16 | | |
| U32 | 74LS151 | 8 | 16 | | |
| U33 | 74S38 | 7 | 14 | | |
| U34 | 74LS04 | 7 | 14 | | |
| U35 | 74LS393 | 7 | 14 | | |
| U36 | 74LS14 | 7 | 14 | | |
| U37 | 74LS174 | 8 | 16 | | |
| U38 | 74LS04 | 7 | 14 | | |

| REF DES | TYPE | GND | +5V | +12V | -12V |
|---------|---------|-----|-----|------|------|
| U39 | 74S04 | 7 | 14 | | |
| U40 | 74S04 | 7 | 14 | | |
| U41 | 74LS27 | 7 | 14 | | |
| U42 | 74LS374 | 10 | 20 | | |
| U43 | 74LS08 | 7 | 14 | | |
| U44 | 74LS08 | 7 | 14 | | |
| U45 | 74S38 | 7 | 14 | | |
| U46 | 74S32 | 7 | 14 | | |
| U47 | K1135B | 11 | 2 | 9 | |
| U48 | 74LS00 | 7 | 14 | | |
| U49 | 74LS164 | 7 | 14 | | |
| U50 | 74S140 | 7 | 14 | | |
| U51 | 74LS09 | 7 | 14 | | |
| U52 | 74LS244 | 10 | 20 | | |
| U53 | MC68B40 | 1 | 14 | | |
| U54 | 74S02 | 7 | 14 | | |
| U55 | 74LS244 | 10 | 20 | | |
| U56 | MC1488 | 7 | | 14 | |
| U57 | MS68B50 | 1 | 12 | | |
| U58 | 74S00 | 7 | 14 | | |
| U59 | 74LS244 | 10 | 20 | | |
| U60 | MC1489 | 7 | 14 | | |
| U61 | 74S10 | 7 | 14 | | |
| U62 | 74LS194 | 8 | 16 | | |
| U63 | 74LS245 | 10 | 20 | | |
| DL1 | 50NS DL | 7 | 14 | | |
| DL2 | 70NS DL | 7 | 14 | | |
| Y1 | K1148A | 7 | 14 | | |
| XU1 | SOCKET | 14 | 28 | | |
| XU2 | SOCKET | 14 | 28 | | |
| XU3 | SOCKET | 14 | 28 | | |
| XU4 | SOCKET | 14 | 28 | | |
| XU5 | SOCKET | 14 | 28 | | |
| XU6 | SOCKET | 14 | 28 | | |
| XU7 | SOCKET | 14 | 28 | | |
| XU8 | SOCKET | 14 | 28 | | |

| | |
|------------------------|----------|
| Y1 | |
| XU8 | |
| U63 | |
| S2 | |
| R22 | |
| P2 | |
| J27 | |
| DS3 | |
| DL2 | |
| C45 | |
| HIGHEST NUMBER USED | NOT USED |
| REFERENCE DESIGNATIONS | |

63EW3047B REV E SH 1 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 1 of 14)

5-17/5-18

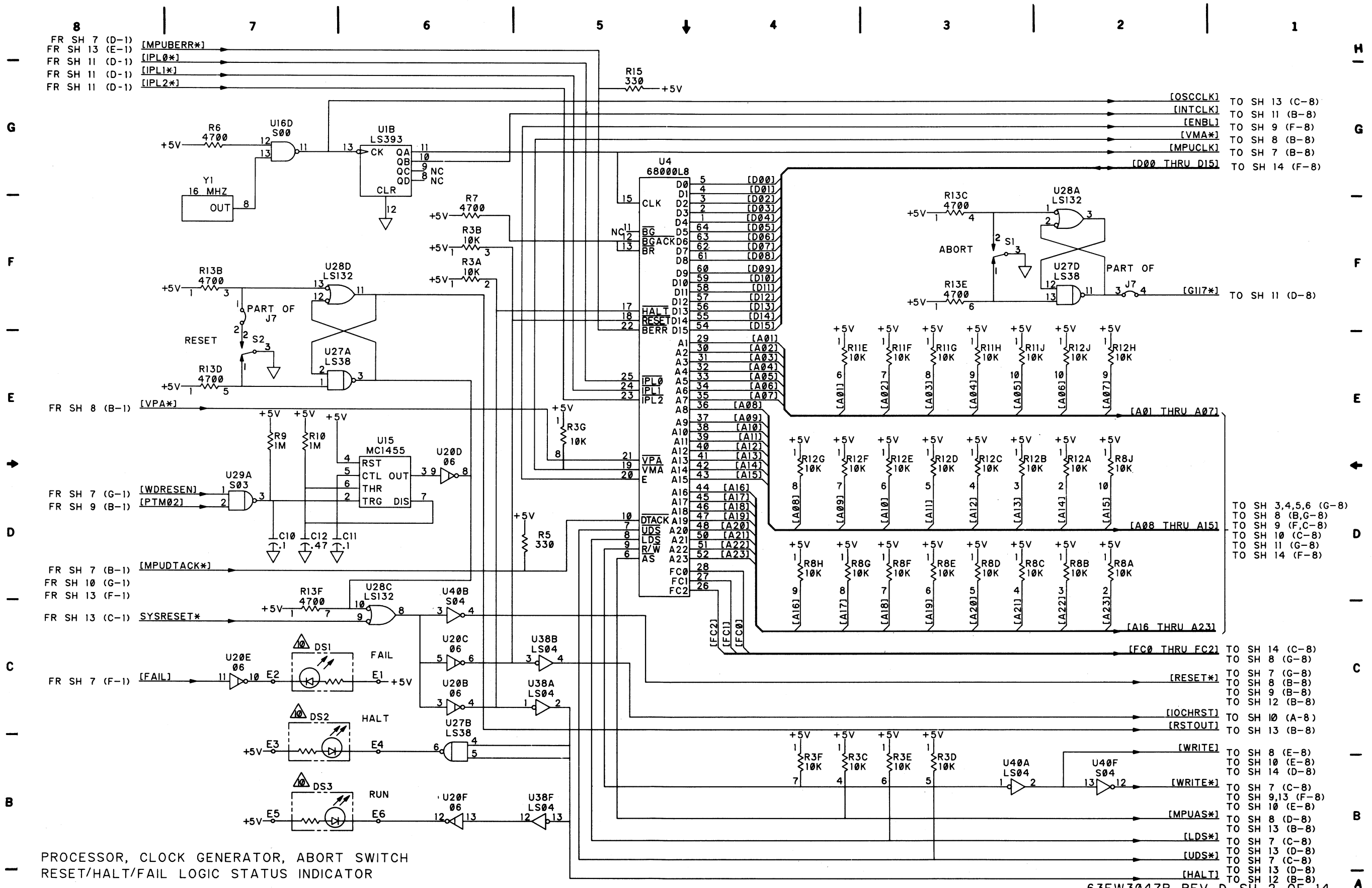
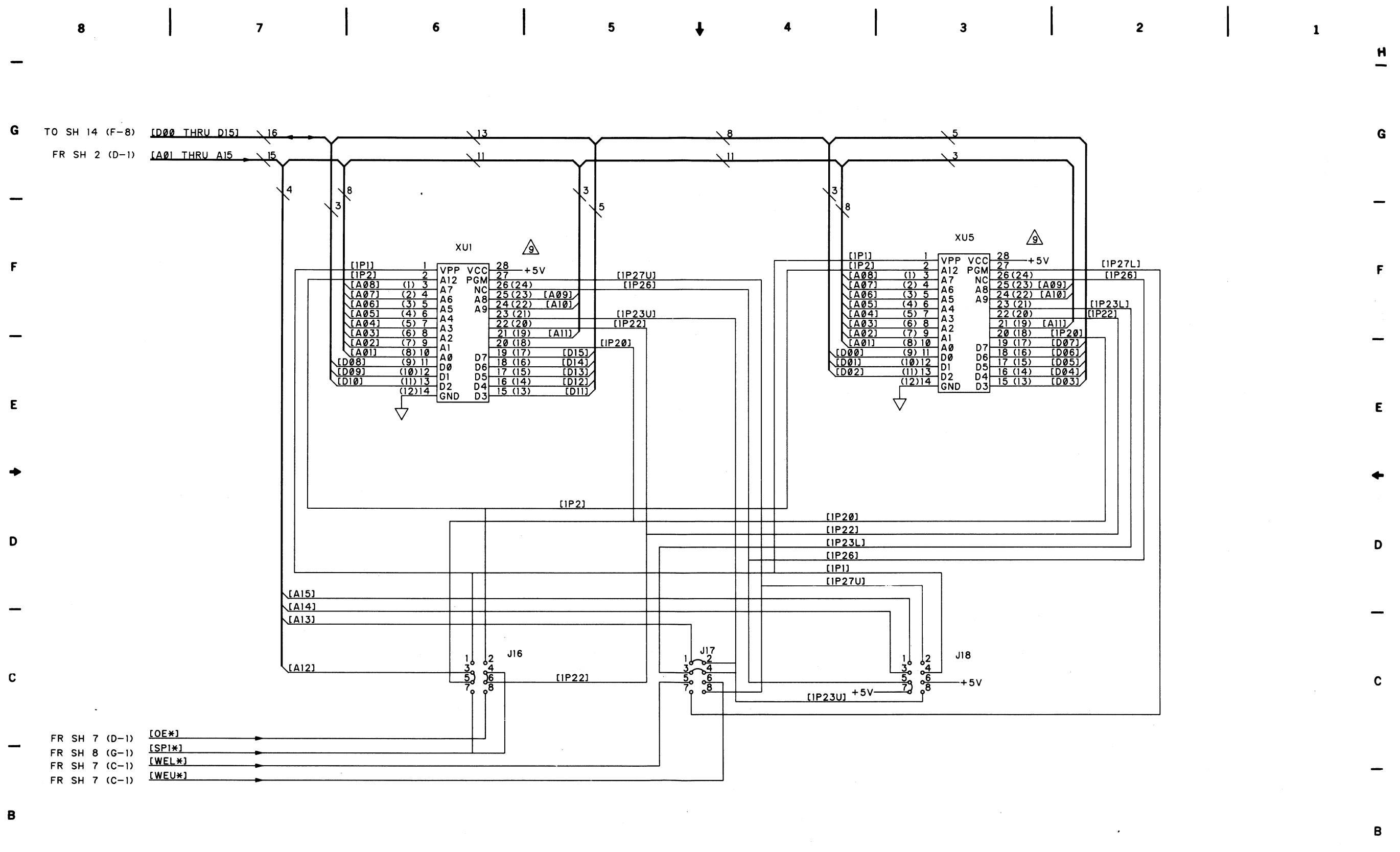
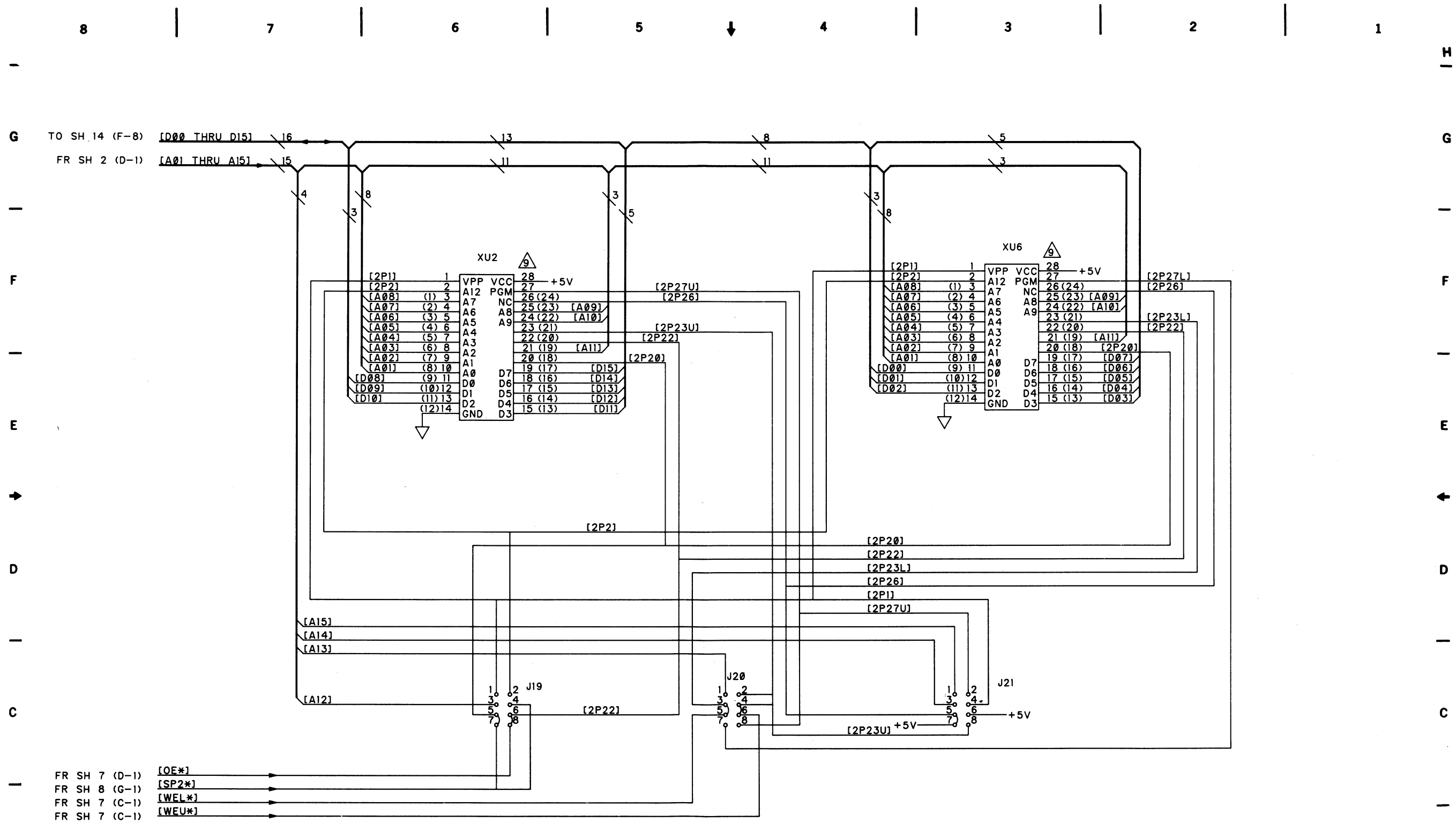


FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 2 of 14)



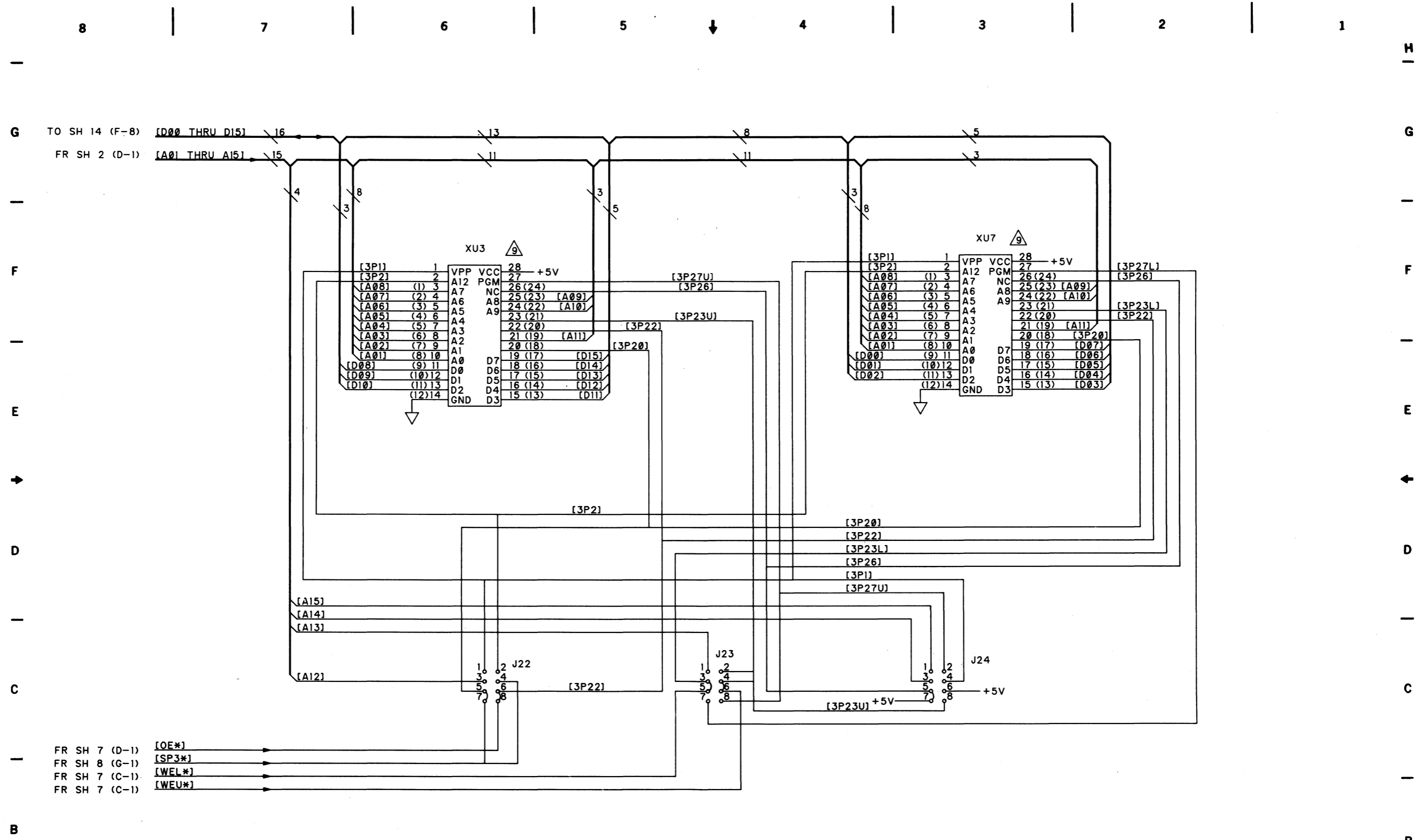
RAM/ROM
63EW3047B REV D SH 3 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 3 of 14)



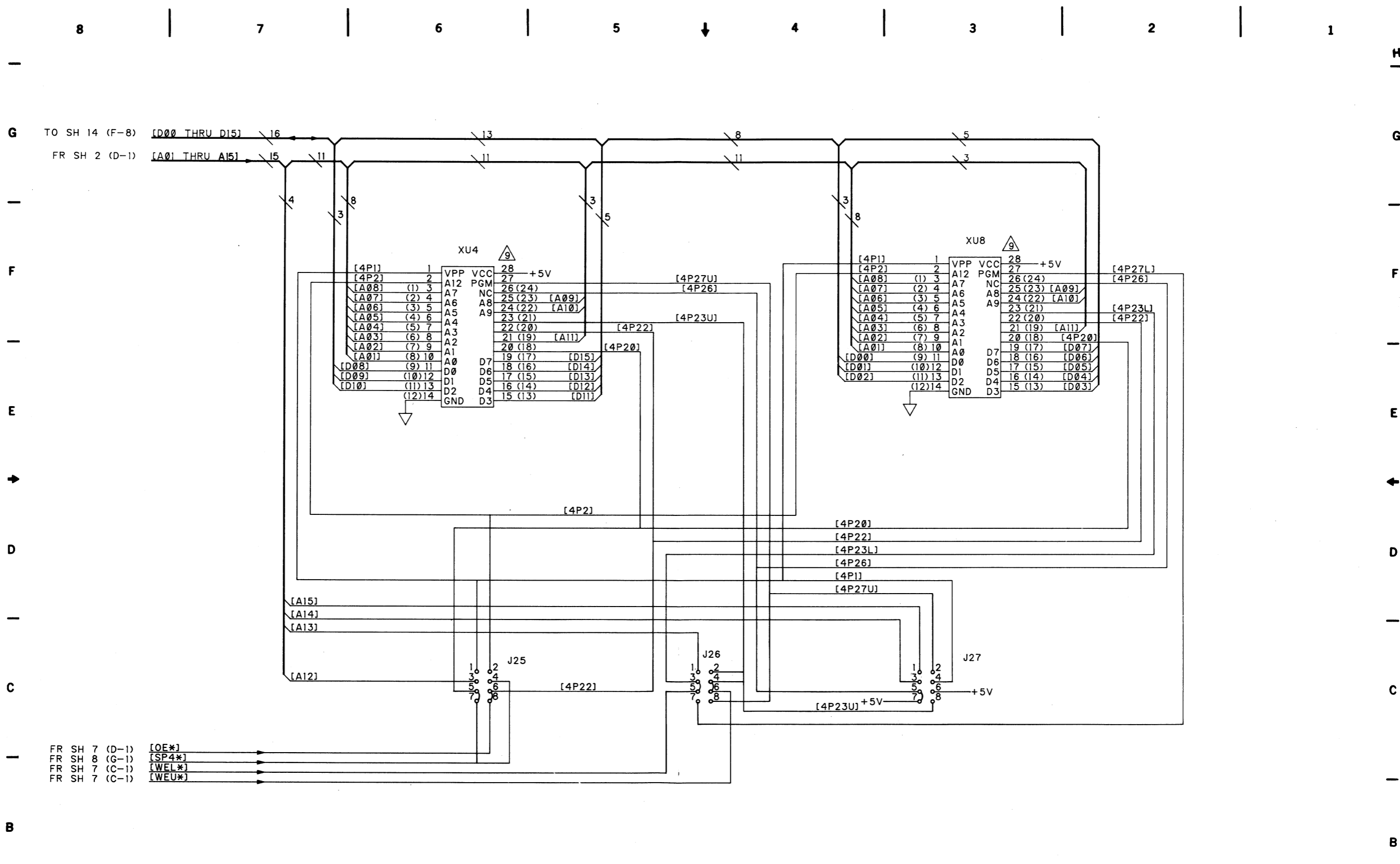
RAM/ROM
63EW3047B REV D SH 4 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 4 of 14)



RAM/ROM
63EW3047B REV D SH 5 OF 14

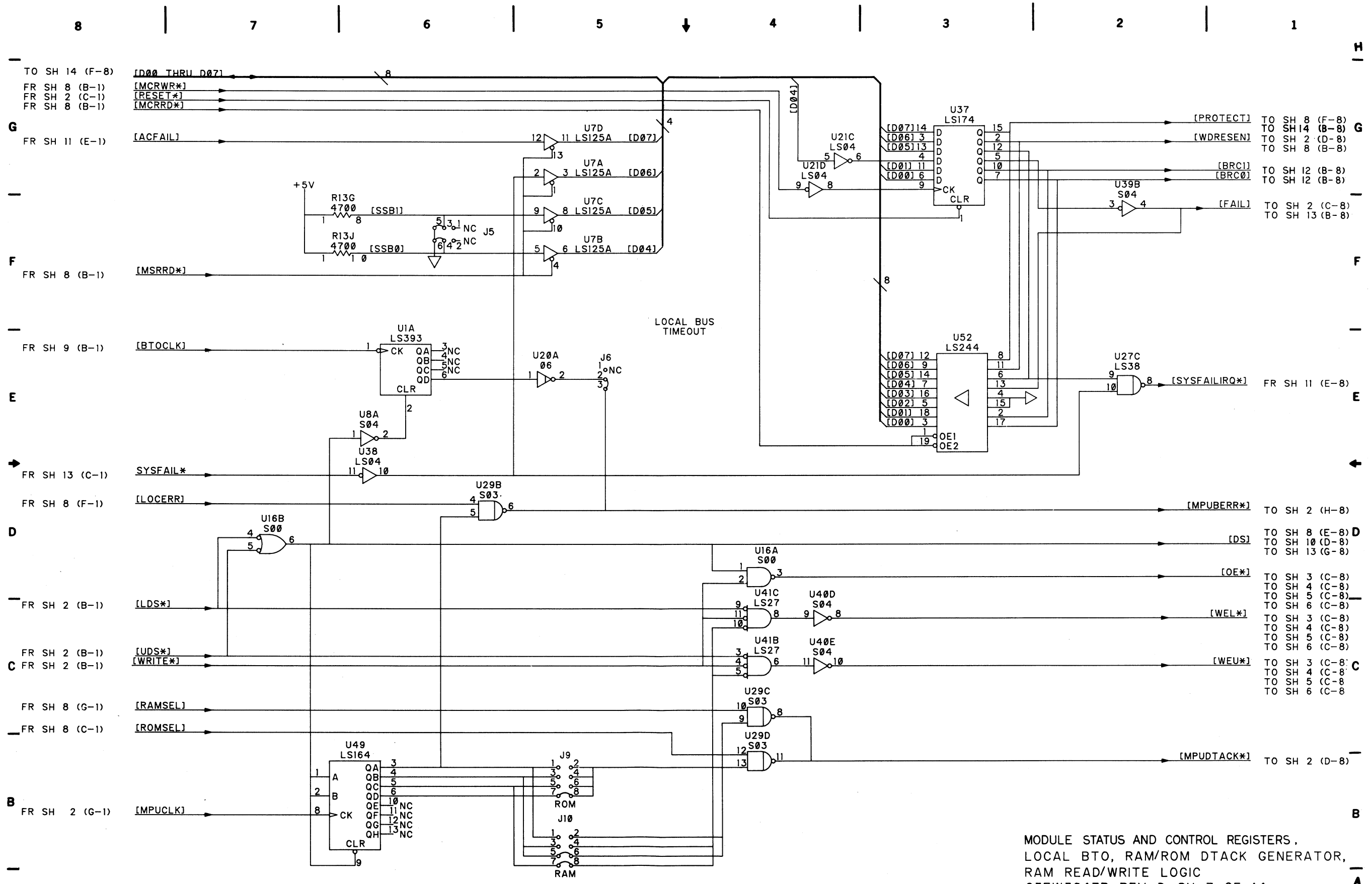
FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 5 of 14)



RAM/ROM
63EW3047B REV D SH 6 OF 14

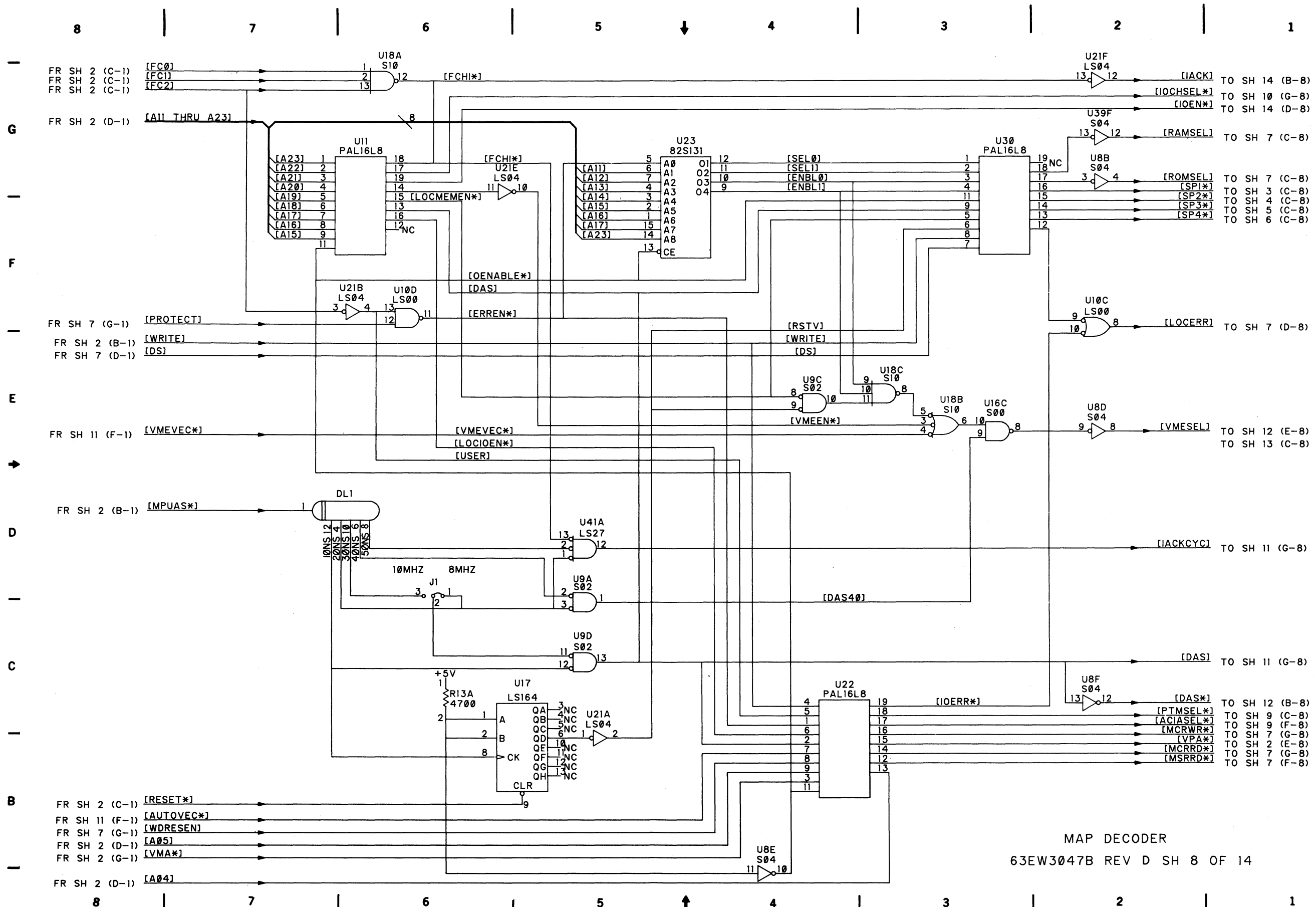
FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 6 of 14)

5-27/5-28



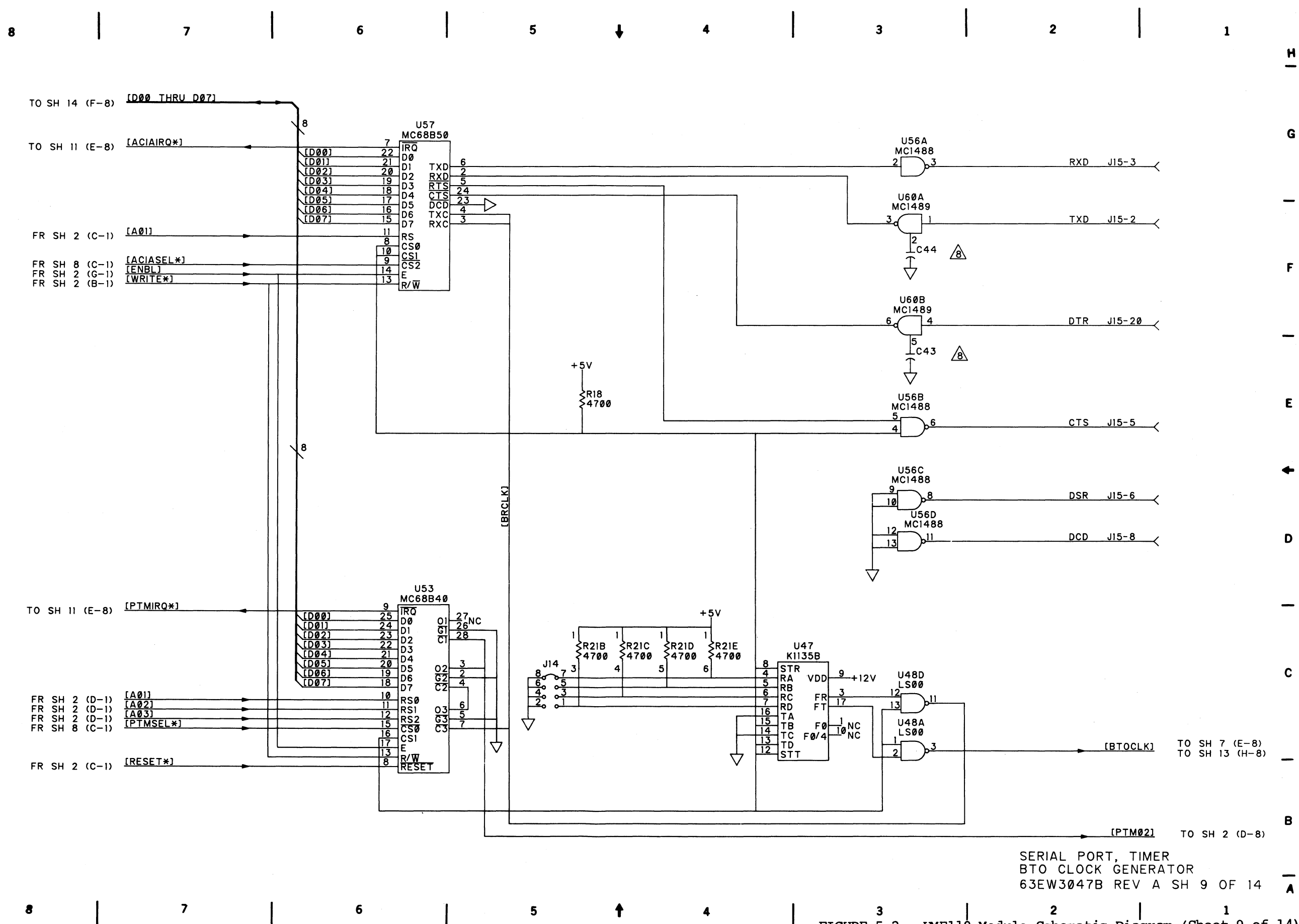
MODULE STATUS AND CONTROL REGISTERS,
 LOCAL BTO, RAM/ROM DTACK GENERATOR,
 RAM READ/WRITE LOGIC
 63EW3047B REV D SH 7 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 7 of 14)



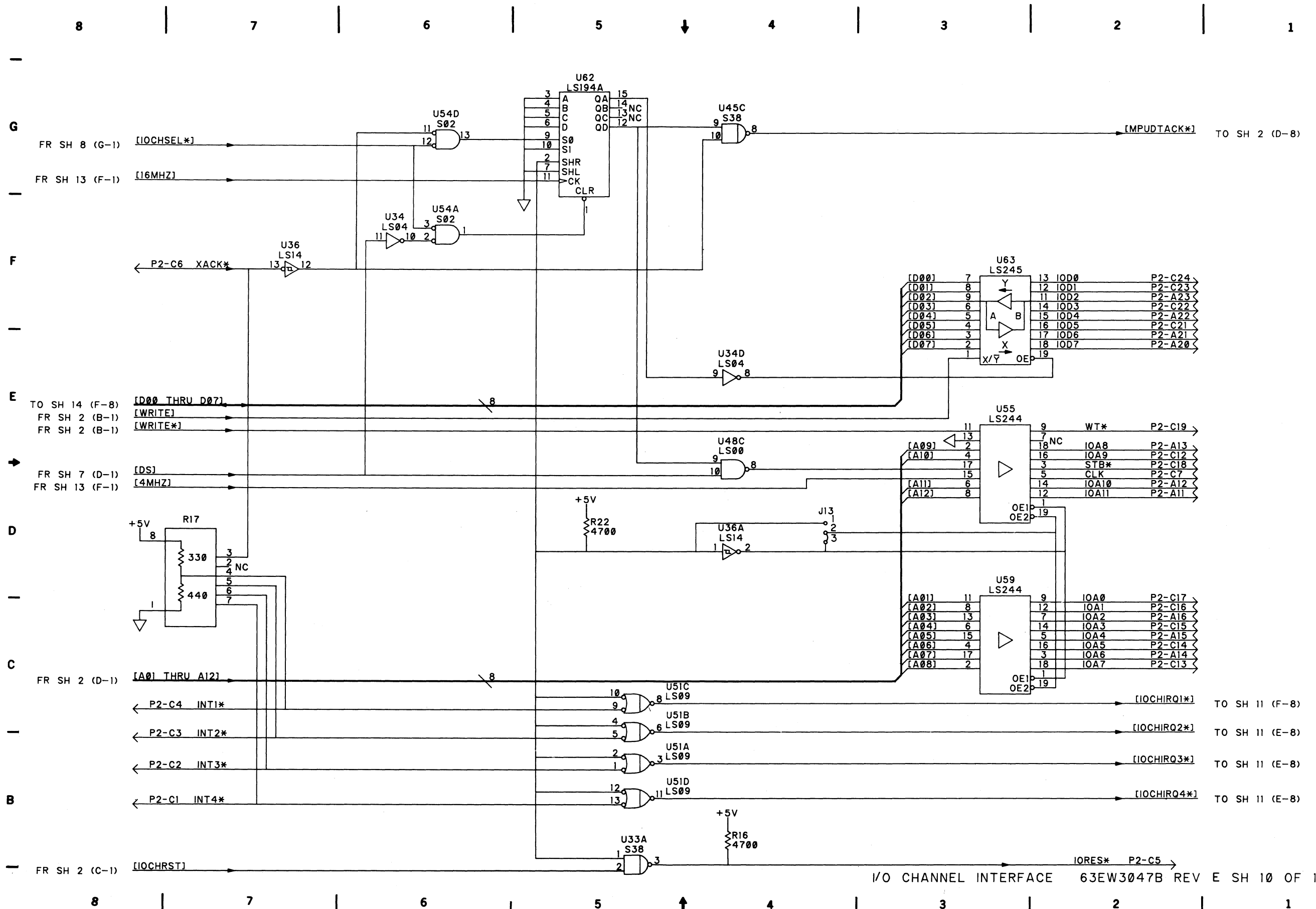
MAP DECODER
63EW3047B REV D SH 8 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 8 of 14)

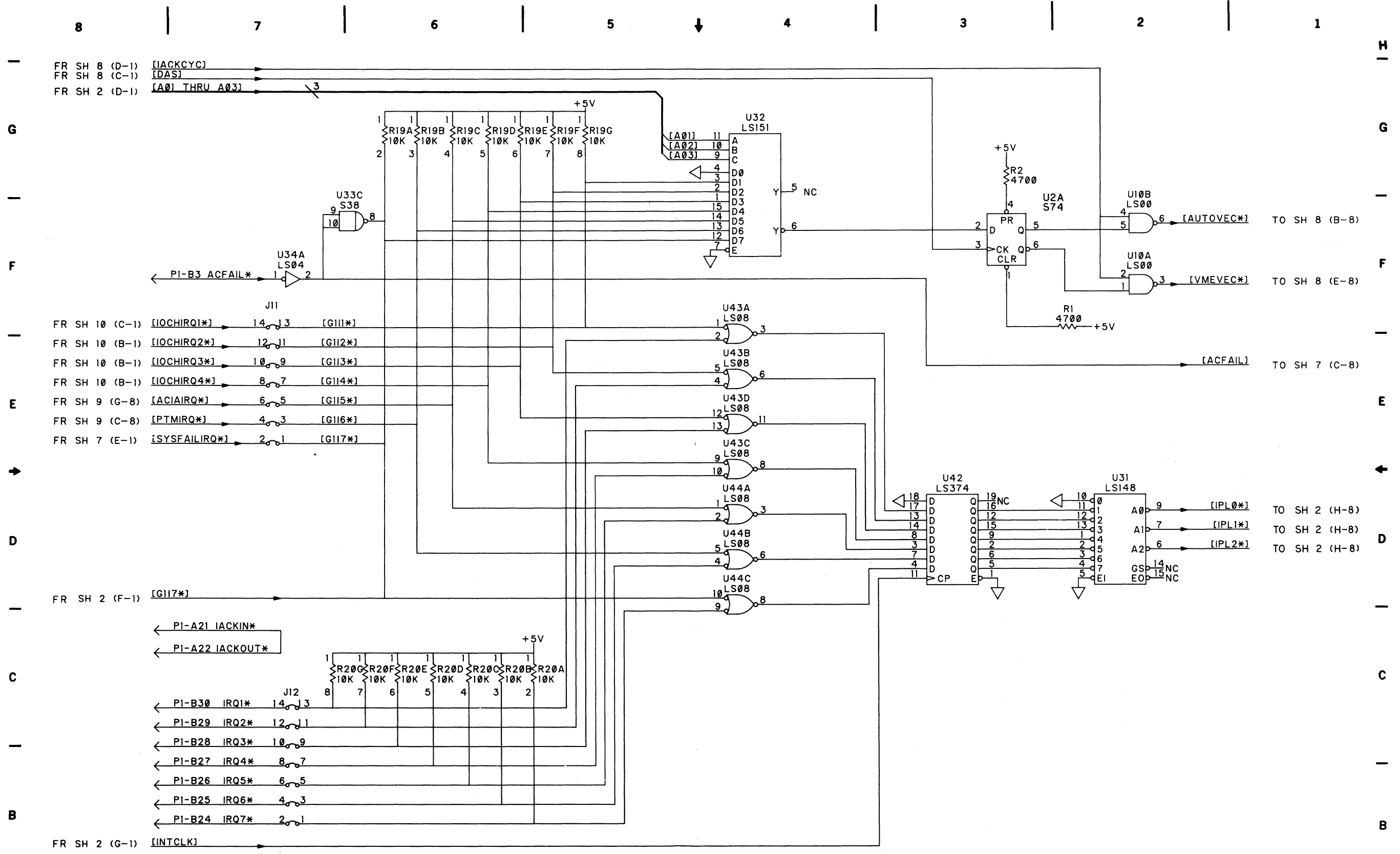


SERIAL PORT, TIMER
 BTO CLOCK GENERATOR
 63EW3047B REV A SH 9 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 9 of 14)



I/O CHANNEL INTERFACE 63EW3047B REV E SH 10 OF 14
 FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 10 of 14)



INTERRUPT HANDLER
63EW3047B REV A SH 11 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 11 of 14)

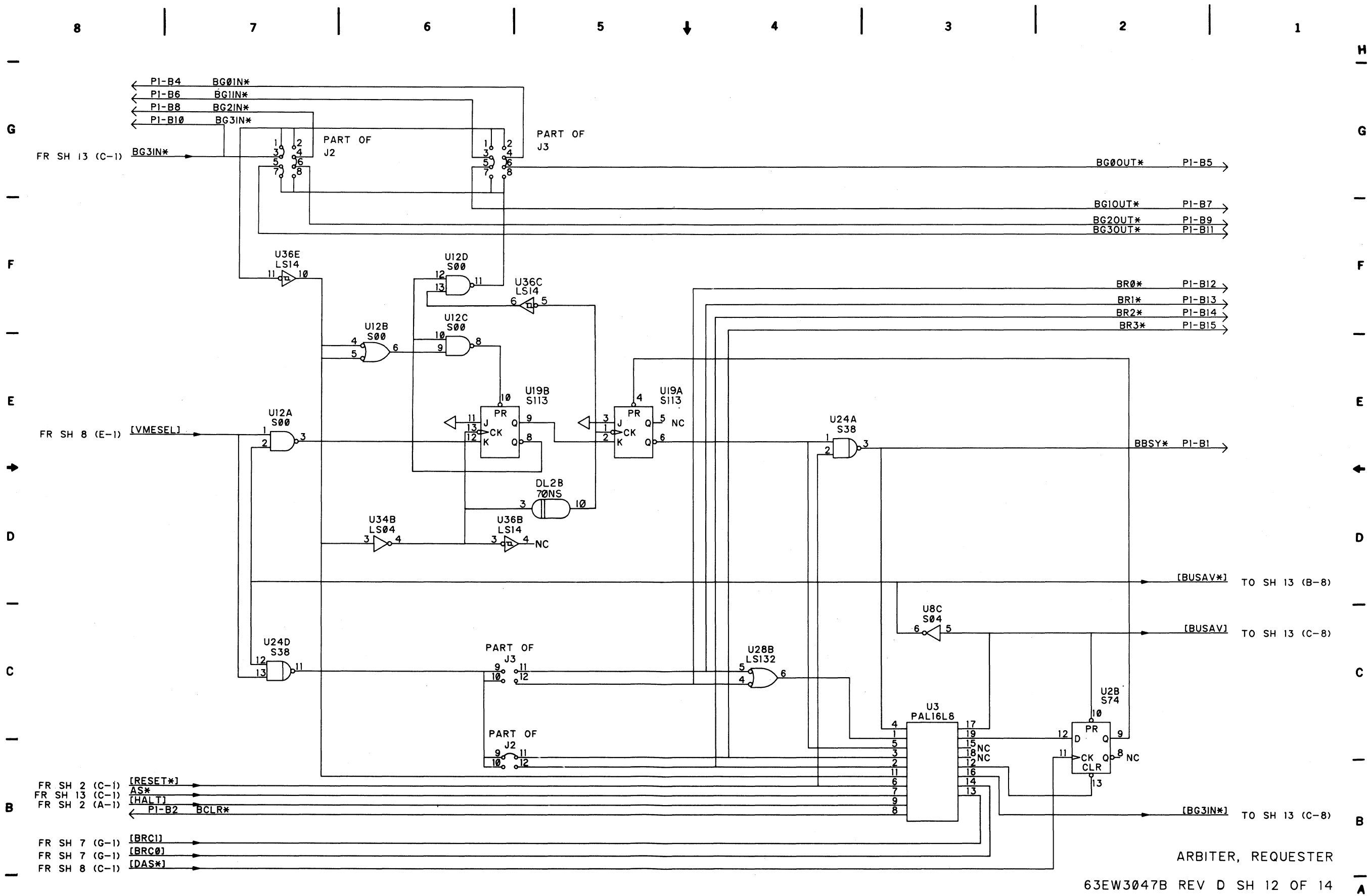
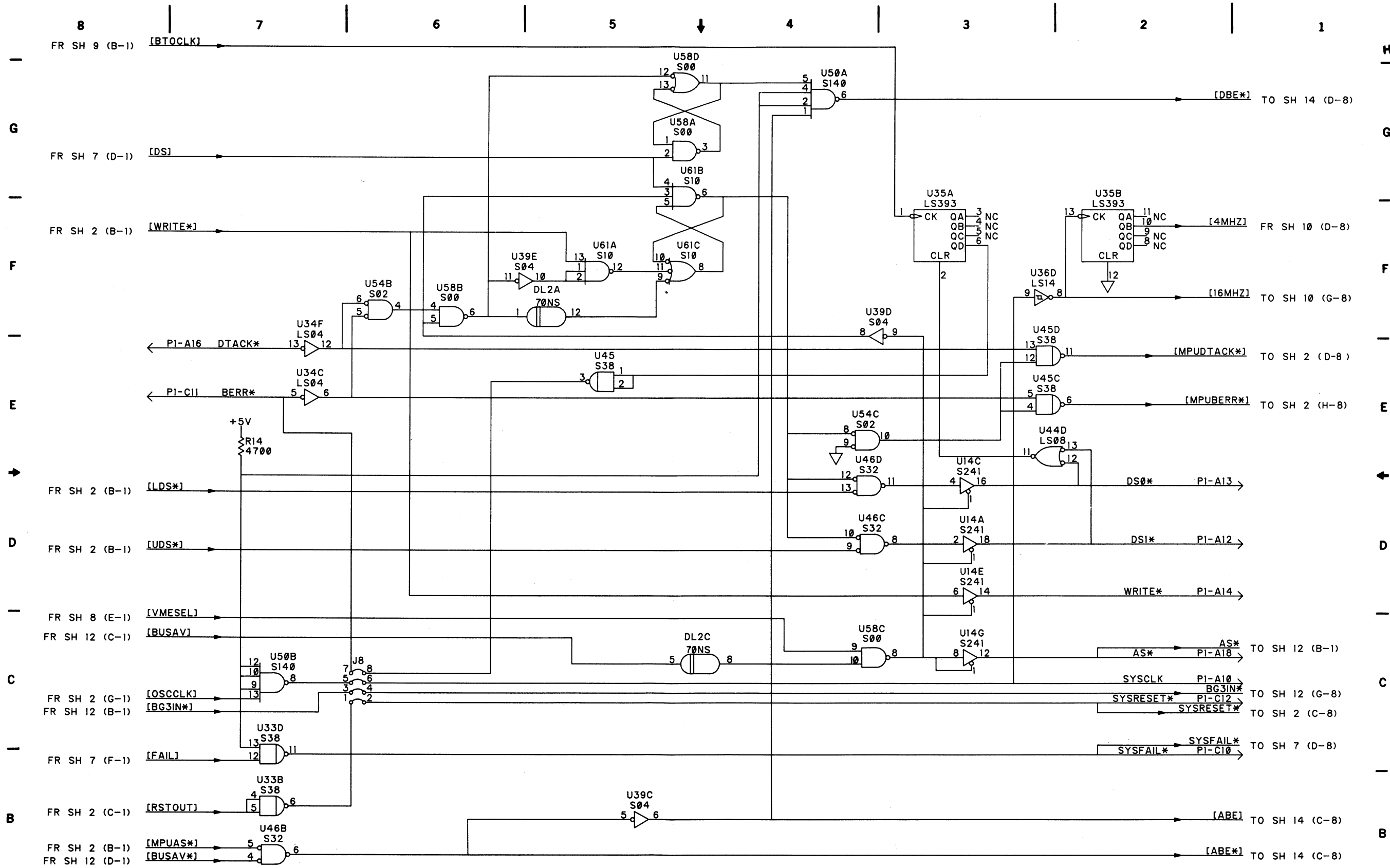


FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 12 of 14)

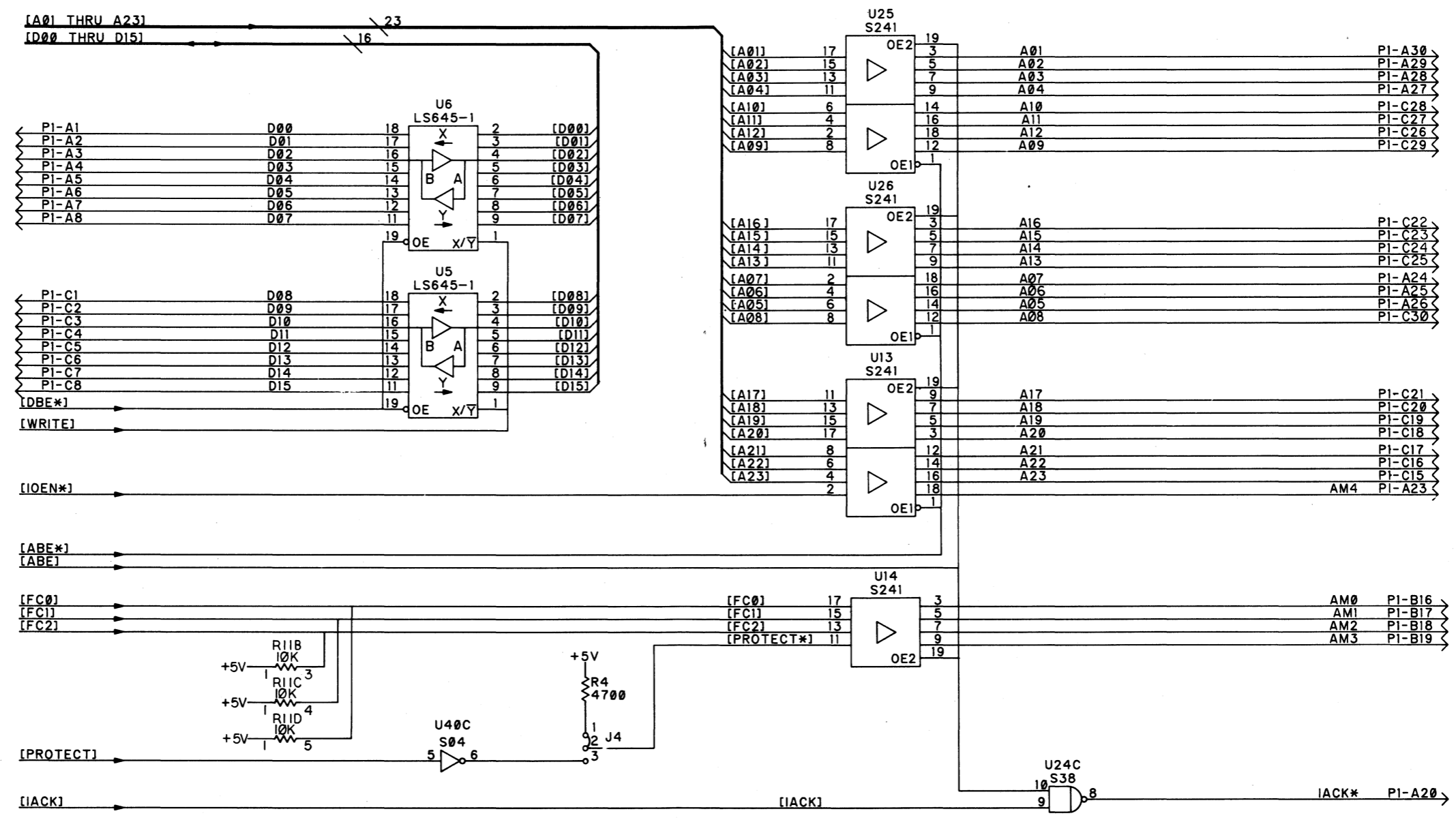


VME INTERFACE
 63EW3047B REV D SH 13 OF 14
 FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 13 of 14)
 5-41/5-42

8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

G

FR SH 2 (D-1)
FR SH 2 (G-1)
FR SH 3,4,5,6 (G-1)
FR SH 7 (H-8)
FR SH 9 (G-8)
FR SH 10 (E-8)



E

FR SH 13 (G-1)
FR SH 2 (B-1)

FR SH 2 (C-1)
FR SH 2 (C-1)
FR SH 2 (C-1)

FR SH 7 (G-1)

FR SH 8 (G-1)

B

8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

VME INTERFACE
63EW3047B REV D SH 14 OF 14

FIGURE 5-2. VME110 Module Schematic Diagram (Sheet 14 of 14)